Electronic Acknowledgement Receipt				
EFS ID:	8248406			
Application Number:	10587725			
International Application Number:				
Confirmation Number:	2259			
Title of Invention:	Method for Manufacturing Soi Wafer			
First Named Inventor/Applicant Name:	Etsuro Morita			
Customer Number:	23581			
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Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)			
1	Information Disclosure Statement (IDS) Filed (SB/08)	20100818_Third_Supplemental _IDS_SB08a-EFS_as-		no	4			
Warnings:		filed_SHX373.pdf	07-e25299v38295b3dd4491607f122621f75 4f258					

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	ge File Wrapper (IFW) system. However, no Non Patent Literature will be manually rev			ich as Foreigr	n Patent
		JP0411551 Suzuki w-English-	888638		_
2	Foreign Reference	abs.pdf	c09de4fee70b467963281550ae23c259368 9db8a	no	5
Warnings:					
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3	Foreign Reference	JP04206766_Shigeniwa_w- English-abs.pdf	1326539	no	7
			5c8d7ae1b819\.707bac94e928028c0be926 378cd		
Warnings:					
nformation:					
4	Foreign Reference	WO93-20584_Gassel_etal_w- English-abs.pdf	4183441	no	20
			1850e51ff235f761fb4a0465982d61ecbfcc5 41c		
Warnings:					
nformation:					
5	Foreign Reference	JP07226433_Hashimoto_w-	3441981	no	13
		English-abs.pdf	81c/99209ec/40c042465e0557424de9fb82s 94bd		
Warnings:					
nformation:					
6	NPL Documents	GASSEL_etal_SIMOX_and_Waf er_Bonding.pdf	1889710	no	2
			Sea2914b6ace13934b64a54d536aeb88f2b 73840		
Warnings:					
Information:					
7 NPL Docum	NPI Documents	TONG_etal_VLSI_SOI_Fabricati on_by_SIMOX_Wafer_Bonding. pdf	718360	no	2
	W E Bocamento		fbbc3980d2d6f54804a/8ba/90145461deb7 22af		
Warnings:					
nformation:					
8	NPL Documents	YANG_etal_Silicon-on- Insulator-with-Active- Substrate.pdf	730908	no	2
			1127ee236983aadf0dcbed35b8ce4e8ca68 55868		
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		Total Files Size (in hytes)	137	22080	

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## New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-[d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

## National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

## New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.